IN THE CLAIMS:

Claims 1-20 have been amended herein. All of the pending claims 1 through 20 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Currently Amended) A method for designing a rerouting element for use with a semiconductor device including at least one bond pad positioned substantially centrally on a surface thereof, comprising:

configuring at least one contact location on a first surface of a substantially planar member, ~~said~~ the at least one contact location mirroring a position of the at least one bond pad on the surface of the semiconductor device;

configuring at least one conductive trace location extending from ~~said~~ the at least one contact location toward a periphery of ~~said~~ the substantially planar member; and

configuring at least one rerouted bond pad location proximate ~~said~~ the periphery, ~~said~~ the at least one rerouted bond pad location being configured to be exposed beyond a periphery of another semiconductor device upon positioning ~~said~~ the another semiconductor device over the surface of the semiconductor device.

2. (Currently Amended) The method of claim 1, wherein ~~said~~ configuring at least one contact location comprises configuring a plurality of contact locations, each contact location of ~~said~~ the plurality of contact locations mirroring a location of a corresponding bond pad on the surface of the semiconductor device.

3. (Currently Amended) The method of claim 2, wherein ~~said~~ configuring at least one conductive trace location comprises configuring a plurality of conductive trace locations, each conductive trace location of ~~said~~ the plurality of conductive trace locations extending from a corresponding contact location toward ~~said~~ the periphery of ~~said~~ the substantially planar member.

4. (Currently Amended) The method of claim 3, ~~wherein~~ comprising configuring each conductive trace location of ~~said~~ the plurality of conductive trace locations ~~extends~~ to extend toward a single edge of ~~said~~ the substantially planar member.

5. (Currently Amended) The method of claim 3, wherein ~~said~~ configuring at least one rerouted bond pad location comprises configuring a plurality of rerouted bond pad locations, each rerouted bond pad location of ~~said~~ the plurality of rerouted bond pad locations being continuous with an end of a corresponding conductive trace location and located proximate ~~said~~ the periphery of ~~said~~ the substantially planar member.

6. (Currently Amended) The method of claim 5, ~~wherein~~ comprising configuring each rerouted bond pad location of ~~said~~ the plurality of rerouted bond pad locations is configured to be exposed beyond a periphery of ~~said~~ the another semiconductor device upon positioning of ~~said~~ the another semiconductor device over the surface of the semiconductor device.

7. (Currently Amended) The method of claim 1, wherein ~~said~~ configuring ~~said~~ the at least one rerouted bond pad location comprises configuring ~~said~~ the at least one rerouted bond pad location to facilitate connection of a discrete conductive element thereto with ~~said~~ the another semiconductor device positioned over the surface of the semiconductor device.

8. (Currently Amended) A method for assembling semiconductor devices in a stacked arrangement, comprising:

providing a semiconductor device with at least one bond pad positioned substantially centrally on a surface thereof; and

positioning a rerouting element over ~~said~~ the surface of ~~said~~ the semiconductor device with a contact of ~~said~~ the rerouting element communicating with ~~said~~ the at least one bond pad, a circuit trace of ~~said~~ the rerouting element extending laterally toward a periphery of ~~said~~ the semiconductor device and establishing communication between ~~said~~ the at least one

bond pad and at least one rerouted bond pad located proximate a periphery of ~~said~~ the semiconductor device at a location where ~~said~~ the at least one rerouted bond pad will remain exposed upon positioning another semiconductor device over ~~said~~ the surface of the semiconductor device.

9. (Currently Amended) The method of claim 8, wherein ~~said~~ providing ~~said~~ the semiconductor device comprises providing a semiconductor device with a plurality of bond pads, at least some of which are positioned at substantially central locations on ~~said~~ the surface.

10. (Currently Amended) The method of claim 9, wherein ~~said~~ positioning ~~said~~ the rerouting element comprises positioning a rerouting element comprising:

a plurality of contacts, each contact of ~~said~~ the plurality of contacts being positioned correspondingly to a position of a corresponding bond pad of ~~said~~ the semiconductor device;

a plurality of conductive traces, each conductive trace of ~~said~~ the plurality of conductive traces extending laterally from a corresponding contact of ~~said~~ the plurality of contacts toward ~~said~~ the periphery of ~~said~~ the semiconductor device; and

a plurality of rerouted bond pads, each rerouted bond pad of ~~said~~ the plurality of rerouted bond pads being positioned at an end of a corresponding conductive trace, proximate ~~said~~ the periphery of ~~said~~ the semiconductor device.

11. (Currently Amended) The method of claim 10, wherein ~~said~~ positioning ~~said~~ the rerouting element comprises positioning a rerouting element with each rerouted bond pad of ~~said~~ the plurality of rerouted bond pads being positioned proximate a single peripheral edge of ~~said~~ the semiconductor device.

12. (Currently Amended) The method of claim 10, wherein ~~said~~ positioning ~~said~~ the rerouting element comprises positioning a rerouting element with each rerouted bond pad of ~~said~~

the plurality of rerouted bond pads being positioned to be exposed beyond a periphery of the another semiconductor device upon being positioned over ~~said~~ the surface of ~~said~~ the semiconductor device.

13. (Currently Amended) The method of claim 8, further comprising:

positioning the another semiconductor device over ~~said~~ the rerouting element, ~~said~~ the at least one rerouted bond pad of ~~said~~ the rerouting element being exposed beyond a periphery of ~~said~~ the another semiconductor device.

14. (Currently Amended) The method of claim 13, further comprising:

securing ~~said~~ the semiconductor device to a carrier substrate.

15. (Currently Amended) The method of claim 14, wherein ~~said~~ securing comprises securing ~~said~~ the semiconductor device to at least one of a circuit board, an interposer, an additional semiconductor device, and leads.

16. (Currently Amended) The method of claim 14, further comprising:

positioning at least one discrete conductive element between ~~said~~ the at least one rerouted bond pad and a corresponding contact area of ~~said~~ the carrier substrate.

17. (Currently Amended) The method of claim 16, wherein ~~said~~ positioning comprises at least one of wire bonding, tape-automated bonding, and thermocompression bonding.

18. (Currently Amended) The method of claim 14, further comprising:

encapsulating at least portions of ~~said~~ the semiconductor device, ~~said~~ the another semiconductor device, and regions of ~~said~~ the carrier substrate adjacent to ~~said~~ the semiconductor device.

19. (Currently Amended) The method of claim 18, wherein ~~said~~ encapsulating comprises glob top encapsulating.

20. (Currently Amended) The method of claim 18, wherein ~~said~~ encapsulating comprises one of transfer molding and pot molding.